

NCE N-Channel Super Trench Power MOSFET

Description

The NCEP30T13GU uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

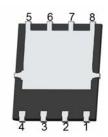
General Features

- V_{DS} =30V, I_D =130A $R_{DS(ON)}$ =1.7mΩ (typical) @ V_{GS} =10V $R_{DS(ON)}$ =2.7mΩ (typical) @ V_{GS} =4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

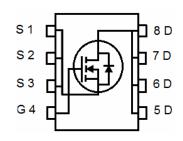
DFN 5X6





Top View

Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P30T13GU	NCEP30T13GU	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous (Silicon Limited)	I _D	130	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	100	Α
Pulsed Drain Current (Package Limited)	I _{DM}	300	Α
Maximum Power Dissipation	P _D	80	W
Derating factor		0.64	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	400	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.56	°C/W
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NCEP30T13GU

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						•
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.2	1.7	2.2	V
Drain Source On State Desigtance		V _{GS} =10V, I _D =65A	-	1.7	1.9	mΩ
Prain-Source On-State Resistance Forward Transconductance Dynamic Characteristics (Note4)	$R_{DS(ON)}$	V _{GS} =4.5V, I _D =65A	-	2.7	3.3	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =65A		60	-	S
Dynamic Characteristics (Note4)						•
Input Capacitance	C _{Iss}	\/ 45\/\/ O\/	-	2394	-	PF
Output Capacitance	C _{oss}	$V_{DS}=15V, V_{GS}=0V,$	-	911	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	50	-	PF
Switching Characteristics (Note 4)						•
Turn-on Delay Time	t _{d(on)}		-	7	-	nS
Turn-on Rise Time	t _r	V_{DD} =15 V , I_{D} =65 A	-	5	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	28	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	\\	-	39.6	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=15V, I_{D}=65A,$	-	5.8		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	6.7		nC
Drain-Source Diode Characteristics			•		<u> </u>	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =65A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	130	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C, I_F = I_S$	-		26	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-		95	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =15V,V $_{\text{G}}$ =10V,L=0.5mH,Rg=25 Ω



Typical Electrical and Thermal Characteristics

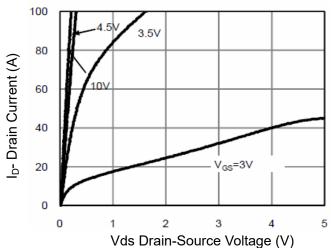


Figure 1 Output Characteristics

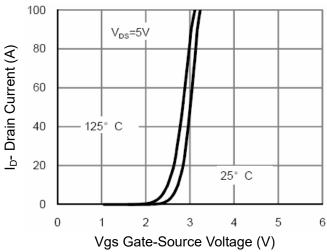


Figure 2 Transfer Characteristics

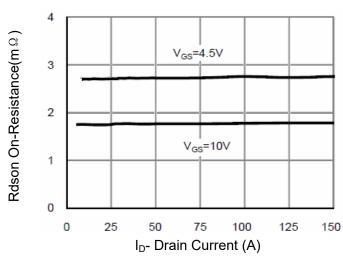


Figure 3 Rdson- Drain Current

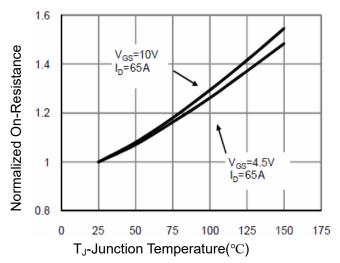


Figure 4 Rdson-Junction Temperature

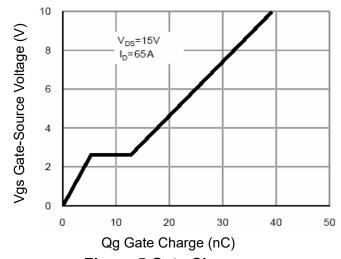


Figure 5 Gate Charge

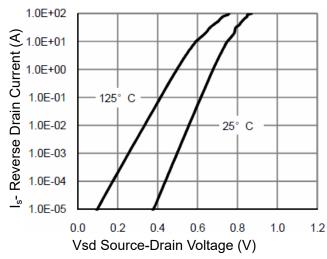


Figure 6 Source- Drain Diode Forward



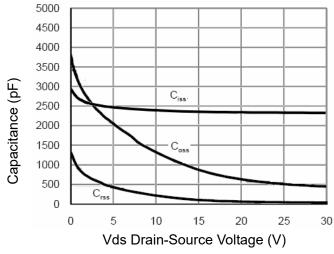


Figure 7 Capacitance vs Vds

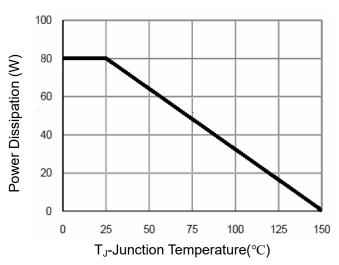


Figure 9 Power De-rating

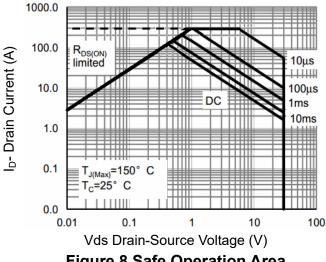


Figure 8 Safe Operation Area

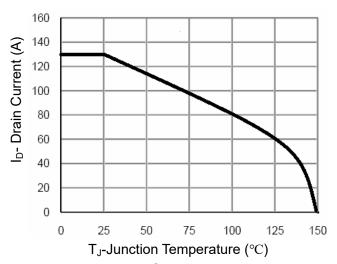


Figure 10 Current De-rating

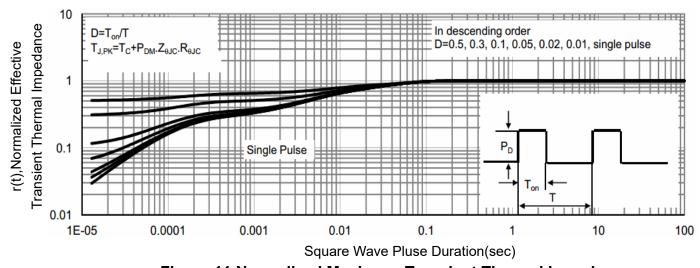
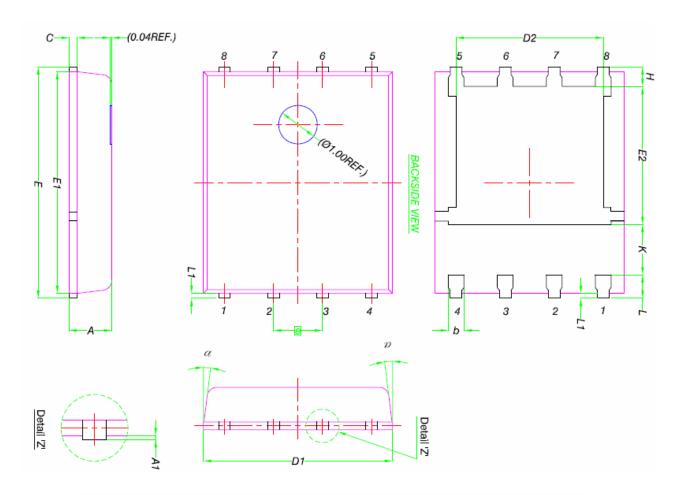


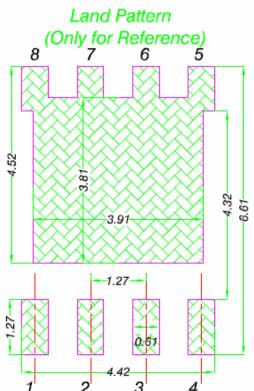
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



5/4	MILLIMETERS				
DIM.	MIN.	NOM.	MAX.		
Α	0.90	1.00	1.10		
A1	0	-	0.05		
b	0.33	0.41	0.51		
С	0.20	0.25	0.30		
D1	4.80	4.90	5.00		
D2	3.61	3.81	3.96		
Ε	5.90	6.00	6.10		
E1	5.70	5.75	5.80		
E2	3.38	3.58	3.78		
е	1.27 BSC				
Н	0.41	0.51	0.61		
K	1.10	-	-		
L	0.51	0.61	0.71		
L1	0.06	0.13	0.20		
α	<i>0</i> °	-	12°		



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NCEP30T13GU

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